



ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
INPUT				
Reverse voltage		V_R	3	V
DC forward current		I_F	25	mA
Surge forward current	$t_p = 1\text{ }\mu\text{s}$, 300 pulses/s	I_{FSM}	1	A
Power dissipation		P_{diss}	45	mW
OUTPUT				
Supply voltage		V_S	- 0.5 to 30	V
Output voltage		V_O	- 0.5 to 25	V
Output current		I_O	8	mA
Power dissipation		P_{diss}	100	mW
COUPLER				
Isolation test voltage between emitter and detector		V_{ISO}	5300	V_{RMS}
Isolation resistance	$V_{IO} = 500\text{ V}$, $T_{amb} = 25\text{ }^{\circ}\text{C}$	R_{IO}	$\geq 10^{12}$	Ω
	$V_{IO} = 500\text{ V}$, $T_{amb} = 100\text{ }^{\circ}\text{C}$	R_{IO}	$\geq 10^{11}$	Ω
Storage temperature range		T_{stg}	- 55 to + 150	$^{\circ}\text{C}$
Ambient temperature range		T_{amb}	- 55 to + 125	$^{\circ}\text{C}$
Junction temperature		T_j	100	$^{\circ}\text{C}$
Soldering temperature (1)	max. 10 s, max. dip soldering: distance to seating plane $\geq 1.5\text{ mm}$	T_{sld}	260	$^{\circ}\text{C}$

Notes

- Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability.

(1) Refer to reflow profile for soldering conditions for surface mounted devices (SMD). Refer to wave profile for soldering conditions for through hole devices (DIP)

ELECTRICAL CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
INPUT (1)						
Forward voltage	$I_F = 16\text{ mA}$	V_F		1.33	1.9	V
Reverse current	$V_R = 3\text{ V}$	I_R		0.5	10	μA
Capacitance	$V_R = 0\text{ V}$, $f = 1\text{ MHz}$	C_O		30		pF
Thermal resistance		R_{thja}		700		K/W
OUTPUT						
Supply current, logic high	$I_F = 0\text{ V}$, $V_O = \text{open}$, $V_{CC} = 15\text{ V}$	I_{CCH}		0.01	1	μA
		I_{CCH}		0.01	2	μA
Output current, output high	$I_F = 0\text{ V}$, $V_O = V_{CC} = 5.5\text{ V}$	I_{OH}		0.003	0.5	μA
	$I_F = 0\text{ V}$, $V_O = V_{CC} = 15\text{ V}$	I_{OH}		0.01	1	μA
		I_{OH}			50	μA
Collector emitter capacitance	$V_{CE} = 5\text{ V}$, $f = 1\text{ MHz}$	C_{CE}		3		pF
Thermal resistance		R_{thja}		300		K/W
COUPLER						
Coupling capacitance		C_C		0.6		pF
Collector emitter saturation voltage	$I_F = 16\text{ mA}$, $I_O = 2.4\text{ mA}$, $V_{CC} = 4.5\text{ V}$	V_{OL}		0.1	0.4	V
Logic low supply current	$I_F = 16\text{ mA}$, $V_O = \text{open}$, $V_{CC} = 15\text{ V}$	I_{CCL}		80	200	μA

Notes

- Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements.

(1) $T_{amb} = 0\text{ }^{\circ}\text{C}$ to $70\text{ }^{\circ}\text{C}$, unless otherwise specified, typical values $T_{amb} = 25\text{ }^{\circ}\text{C}$.

CURRENT TRANSFER RATIO ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Current transfer ratio	$I_F = 16\text{ mA}$, $V_O = 0.4\text{ V}$, $V_{CC} = 4.5\text{ V}$	I_C/I_F	19	30		%
	$I_F = 16\text{ mA}$, $V_O = 0.5\text{ V}$, $V_{CC} = 4.5\text{ V}$, $T_{amb} = 0\text{ }^{\circ}\text{C}$ to $70\text{ }^{\circ}\text{C}$	I_C/I_F	15			%

SWITCHING CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Propagation delay time (high to low), see fig. 1	$I_F = 16\text{ mA}$, $V_{CC} = 5\text{ V}$, $R_L = 1.9\text{ k}\Omega$	t_{PHL}		0.3	0.8	μs
Propagation delay time (low to high), see fig. 1	$I_F = 16\text{ mA}$, $V_{CC} = 5\text{ V}$, $R_L = 1.9\text{ k}\Omega$	t_{PLH}		0.3	0.8	μs

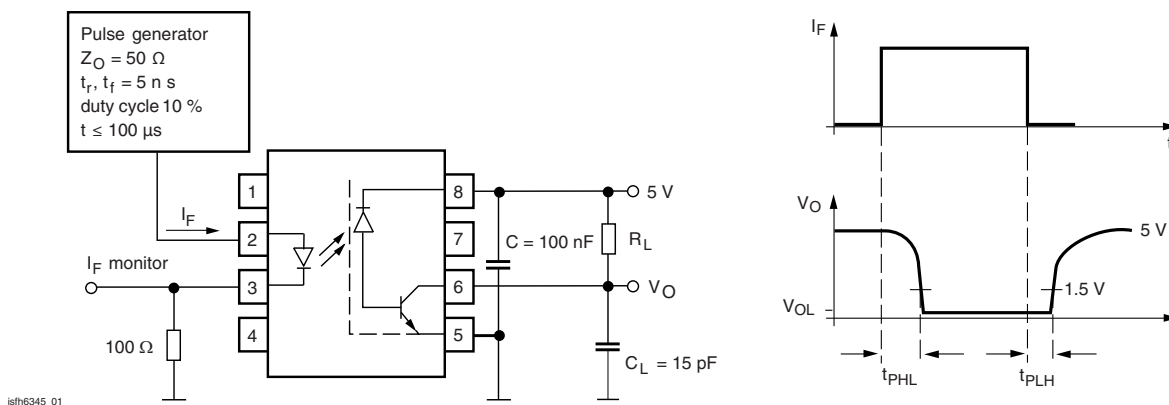


Fig. 1 - Switching Times (Typ.)

COMMON MODE TRANSIENT IMMUNITY ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Common mode transient immunity (high), see fig. 2	$I_O = 0\text{ mA}$, $V_{CM} = 1500\text{ V}_{P-P}$, $R_L = 1.9\text{ k}\Omega$, $V_{CC} = 5\text{ V}$	$ CM_H $	15	30		$\text{kV}/\mu\text{s}$
Common mode transient immunity (low), see fig. 2	$I_O = 16\text{ mA}$, $V_{CM} = 1500\text{ V}_{P-P}$, $R_L = 1.9\text{ k}\Omega$, $V_{CC} = 5\text{ V}$	$ CM_L $	15	30		$\text{kV}/\mu\text{s}$

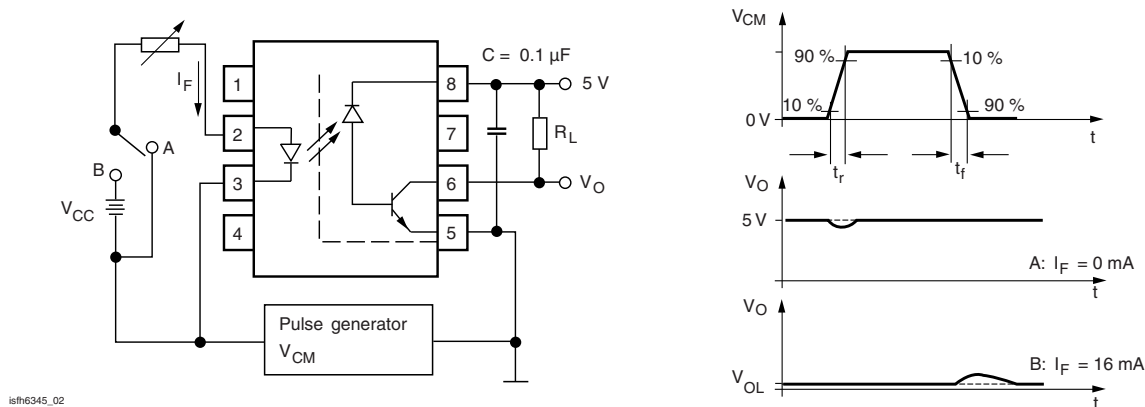


Fig. 2 - Common Mode Transient Immunity

SAFETY AND INSULATION RATINGS						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Climatic classification	IEC 68 part 1			55/100/21		
Comparative tracking index		CTI	175		399	
V_{IOTM}			8000			V
V_{IORM}			890			V
P_{SO}					500	mW
I_{SI}					300	mA
T_{SI}					175	°C
Creepage distance	Standard DIP-8		7			mm
Clearance distance	Standard DIP-8		7			mm
Creepage distance	400 mil DIP-8		8			mm
Clearance distance	400 mil DIP-8		8			mm

Note

- According to DIN EN 60747-5-2 (VDE 0884), this optocoupler is suitable for “safe electrical insulation” only within the safety ratings. Compliance with the safety ratings shall be ensured by means of protective circuits.

TYPICAL CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)


Fig. 3 - LED Forward Current vs. Forward Voltage



Fig. 5 - Permissible Power Dissipation vs. Temperature



Fig. 4 - Permissible Forward LED Current vs. Temperature



Fig. 6 - Output Current vs. Output Voltage

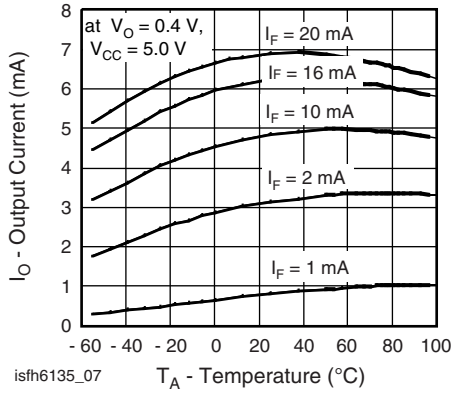


Fig. 7 - Output Current vs. Temperature

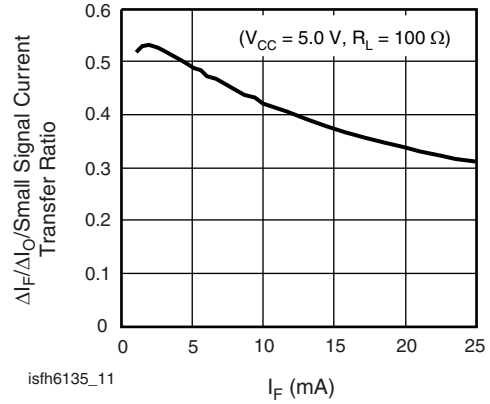


Fig. 10 - Small Signal Current Transfer Ratio vs. Input Current

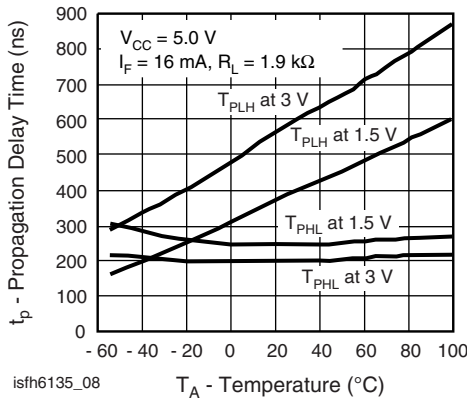


Fig. 8 - Propagation Delay vs. Ambient Temperature

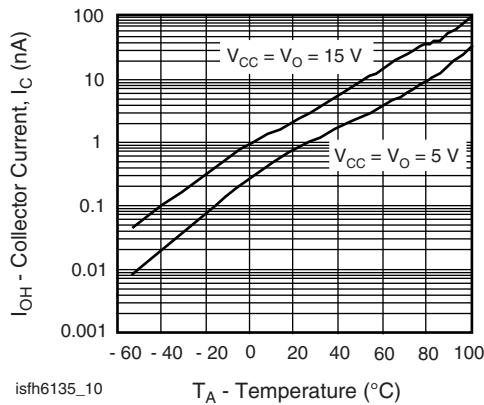
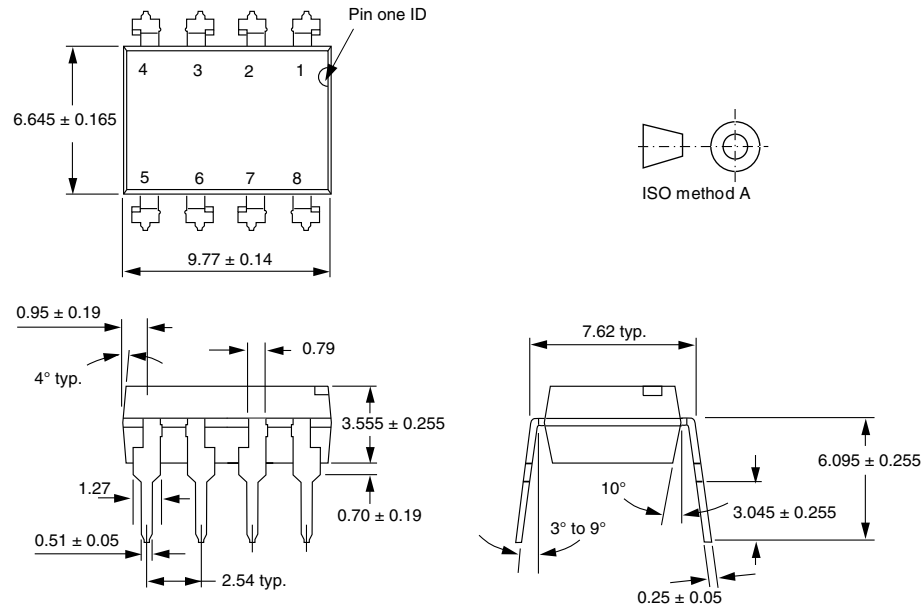


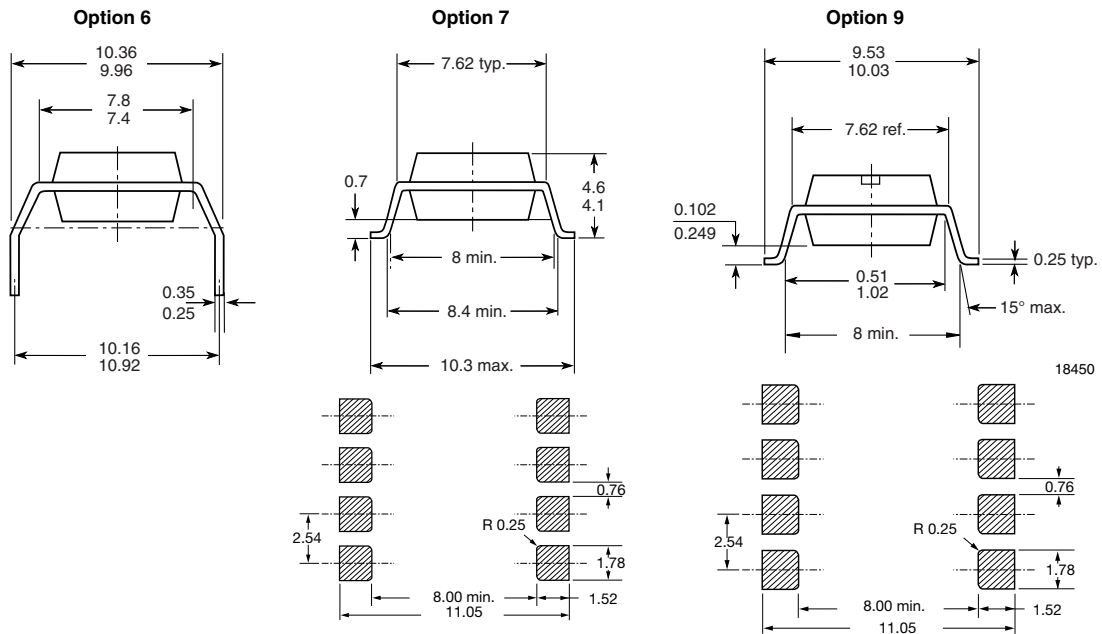
Fig. 9 - Logic High Output Current vs. Temperature



PACKAGE DIMENSIONS in millimeters

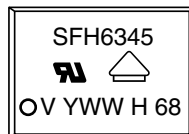


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PACKAGE MARKING



Notes

- Only options 1, and 7 are reflected in the package marking.
- The VDE logo is only marked on option 1 parts.
- Tape and reel suffix (T) is not part of the package marking.



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